1) Lithography Time (sec) **Softbake: Exposure: Developer:** Hardbake: Linewidth (um) of Photoresist Nominal Measured % Overetch 4 Notes: 1 tick mark in the right eyepiece of microscope is 1um under 100X Take a photo of the linewidth marks under 50X **Vernier Misalignment:** X Take 3 Photos: Overall Vernier Pattern under 20X, and zoomed photo of X & Y vernier patterns under 50X 2) Aluminum: Aluminum Etch Time: Linewidth (um) of Al after etch Nominal Measured % Overetch 3 4 Notes: 1 tick mark in the right eyepiece of microscope is 1um under 100X **Sintering:** Time (min) Temperature (C)

EE143 Lab Week 10 Measurement Checklist:

Created: 2006/02/20, Shong Yin

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Calculate % overetch of the linewidth patterns

What was a visual method for determining completion of etching?

Calculate theoretical Al thickness from etch time.

Calculate theoretical Al thickness from the sheet resistance.